

Technical Data Sheet

MODEL NO: Q110YG4 3.0*1.0mm 110 SMD LEDs

Features:

• Compatible with automatic placement equipment

• Compatible with reflow solder process

Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP/GaAs	Yellow Green	Water transparent

Electrical/Optical Characteristics(Ta=25 $^{\circ}$ C)

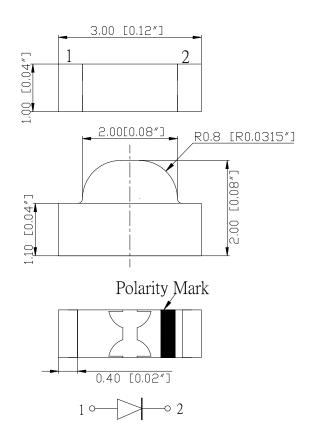
Parameter	Test	Symbol	Value			Unit
	Condition		Min	Тур	Max	Unit
Wavelength at peak emission	IF=20mA	λ peak		572		nm
Spectral half bandwidth	IF=20mA	Δλ		16		nm
Dominant wavelength	IF=20mA	λD	565	570	576	nm
Forward voltage	IF=20mA	VF	1.7	2.0	2.5	V
Luminous intensity	IF=20mA	lv	20	40	63	mcd
Viewing angle at 50% Iv	IF=20mA	2 <i>\theta</i> 1/2		150		Deg
Reverse current	VR=5V	lr			10	μА

Absolute Maximum Ratings(Ta=25°C)

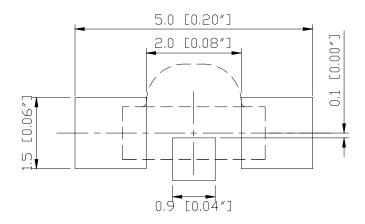
Parameter	Symbol	Value	Unit
Power dissipation	Pd	75	mW
Forward current	lF	30	mA
Reverse voltage	VR	5	V
Operating temperature range	Тор	-40 ~+80	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+100	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/8 duty f=1kHz)	lfp	125	mA



PACKAGING DIMENSIONS



RECOMMEND PAD LAYOUT

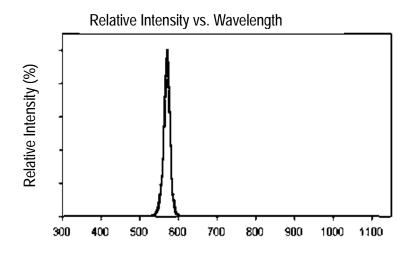


NOTES:

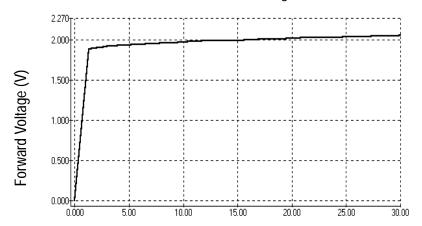
- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are ± 0.1 mm (0.004inch) unless otherwise noted.



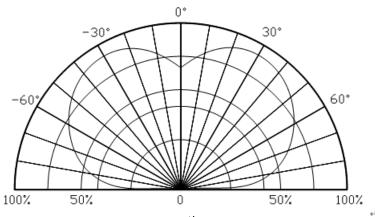
Typical Electro-Optical Characteristics Curve:



Forward Current vs. Forward Voltage



Directive Characteristics



Precautions For Use:

Over - current - proof

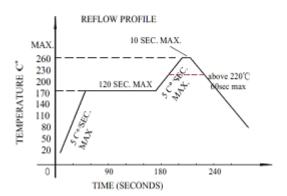
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

- 1. The operation of temperature and R.H. are : 5° C $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C}\pm5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time

Temperature-profile (Surface of circuit board) Use the following conditions shown in the figure.



NOTES:

- 1. We recommend the reflow temperature $245^{\circ}\text{C}(\pm 5^{\circ}\text{C})$.the maximum soldering temperature should be limited to 260°C .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

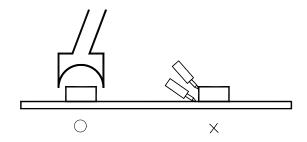
■Soldering iron

Basic spec is $\frac{c}{\lambda}$ 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C.

■Rework

- 1. Customer must finish rework within 5 sec under 260° C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.

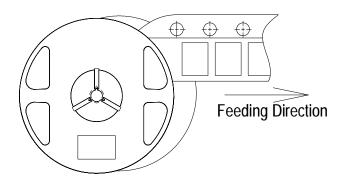




■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.

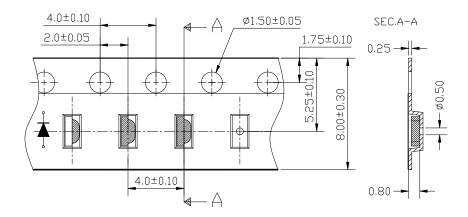


Feeding Direction



Tape specifications

(Units:mm)



Tape specifications

